

AMENDMENTS TO THE CLAIMS

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

Listing of Claims:

- 1-19. (Cancelled)
20. (Original) A MEMS device, comprising:
 - a fixing part fixed to a substrate;
 - a driving part connected to the fixing part by a connecting part and floating over the substrate;
 - an electrode part for driving the driving part; and
 - contact parts selectively switchable with the driving part, wherein the electrode part and the contact parts are planarized on the substrate.
21. (Previously Presented) The MEMS device as claimed in claim 20, wherein the electrode part includes an electrode and an insulation layer covering the electrode to electrically isolate the driving part and the electrode.
22. (Original) The MEMS device as claimed in claim 20, further comprising:
 - an anchor inserted between the fixing part and the substrate for fixing the fixing part on the substrate; and
 - sidewalls on at least a portion of side surfaces of the anchor.
23. (Currently Amended) The MEMS device as claimed in claim 22 [[20]], wherein the sidewalls are substantially formed over the entire portion remaining except for a portion corresponding to the [[a]] connection part connecting the fixing part and the driving part.
24. (Original) The MEMS device as claimed in claim 20, wherein a width of the connection part is narrower than that of the fixing part.

25. (Original) The MEMS device as claimed in claim 22, wherein the sidewalls, fixing part, and driving part are integrally formed in one body.

26. (Original) The MEMS device as claimed in claim 25, wherein the sidewalls are in contact with the substrate.

27. (Previously Presented) The MEMS device as claimed in claim 21, wherein the electrode is embedded in the insulation layer.

28. (Previously Presented) The MEMS device as claimed in claim 27, wherein the insulating layer is integral in a single layer.

29. (Previously Presented-Withdrawn) The MEMS device as claimed in claim 27, wherein the insulating layer includes a first insulating layer around sides of the electrode part and a second insulating layer on top of the electrode part.

30. (Previously Presented) The MEMS device as claimed in claim 22, further comprising a support structure adjacent a sidewall and between the anchor and a contact part under the anchor.

31. (Previously Presented) The MEMS device as claimed in claim 30, wherein the support structure is at least one of aluminum, copper, oxide and nickel.